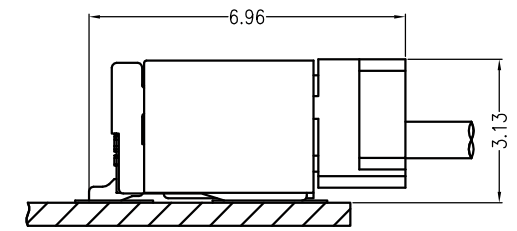
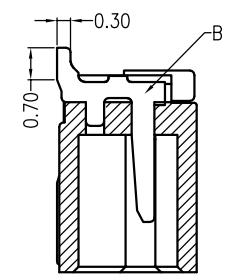
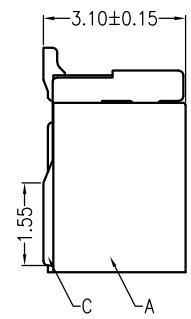
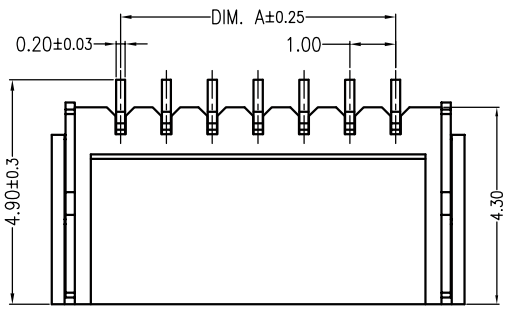
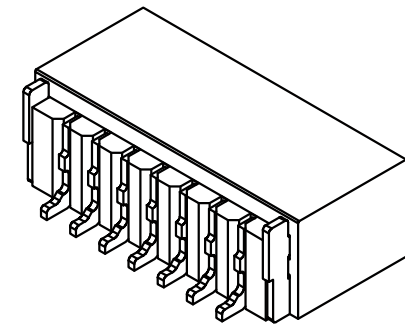
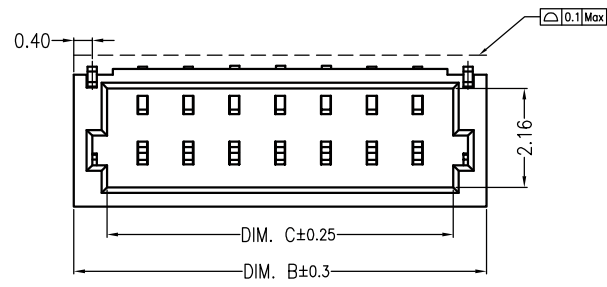


REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2016.05.05
A1		增加镀金规格	吴丹平	2017.03.03

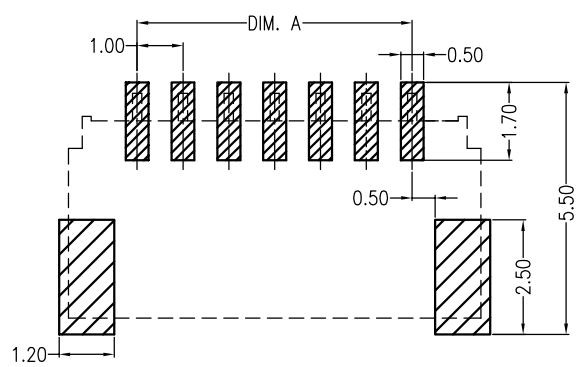


Assembly Layout



主要技术参数 Main Specifications

- 线 数 (Poles): 02 to 20
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 100M\Omega$
- 额定电压 (Rated voltage): 50V AC DC
- 额定电流 (Rated current): 0.5A AC DC
- 耐 电压 (Withstand Voltage): 500V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$



Recommend PCB Layout

Circuit	Dimensions (mm)		
	DIM. A	DIM. B	DIM. C
02	1.00	4.00	2.45
03	2.00	5.00	3.45
04	3.00	6.00	4.45
05	4.00	7.00	5.45
06	5.00	8.00	6.45
07	6.00	9.00	7.45
08	7.00	10.00	8.45
09	8.00	11.00	9.45
10	9.00	12.00	10.45
11	10.00	13.00	11.45
12	11.00	14.00	12.45
13	12.00	15.00	13.45
14	13.00	16.00	14.45
15	14.00	17.00	15.45
16	15.00	18.00	16.45
20	19.00	22.00	20.45

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PHOSPHORBRONZE	**-plated
B	CONTACT	2~20PCS	PHOSPHORBRONZE	**-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn X.±0.5 X.±5' .X±0.3 .X±2' .XX±0.25 .XX±1' -- --		USE: CUSTOMER	TITLE: 1.0mmPITCH 90°WAFER SMT TYPE	
		APPD: 邵敬和	PART NO.:	
DR: 吴丹平 UNITS: mm		CHKD: 田峰	DWG NO.:	
		DR: 吴丹平	SCALE: 1 : 1	SHEET: 1 / 1